

Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Peak Repetitive Reverse Voltage	V _{RRM}	30	V
Working Peak Reverse Voltage	V _{RWM}		
DC Blocking Voltage	V _R		
Average Rectified Output Current (Note 5)	I _O	200	mA
Repetitive Peak Forward Current	I _{FRM}	300	mA
Forward Surge Current @ t < 1.0s	I _{FSM}	600	mA

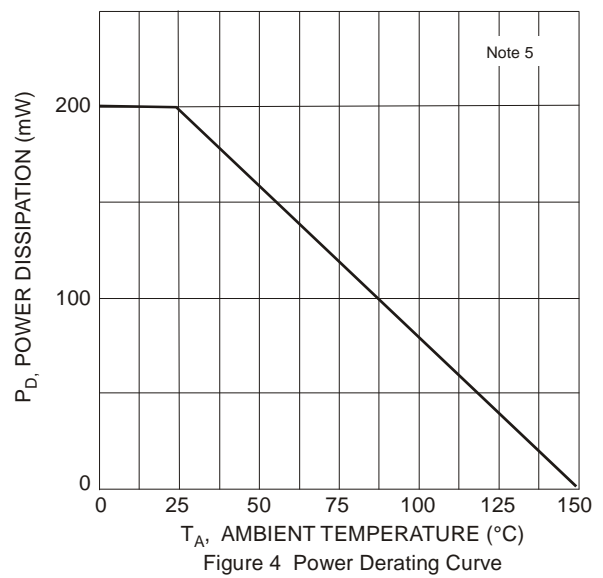
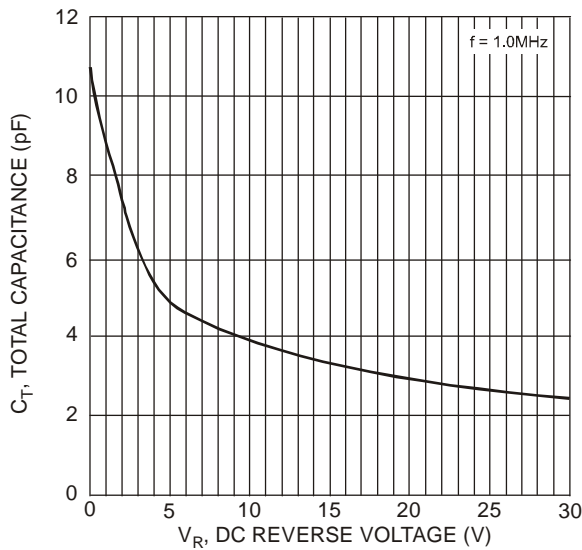
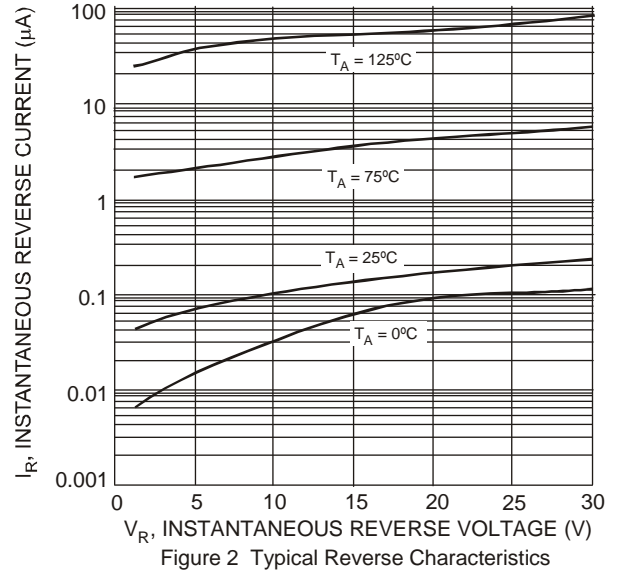
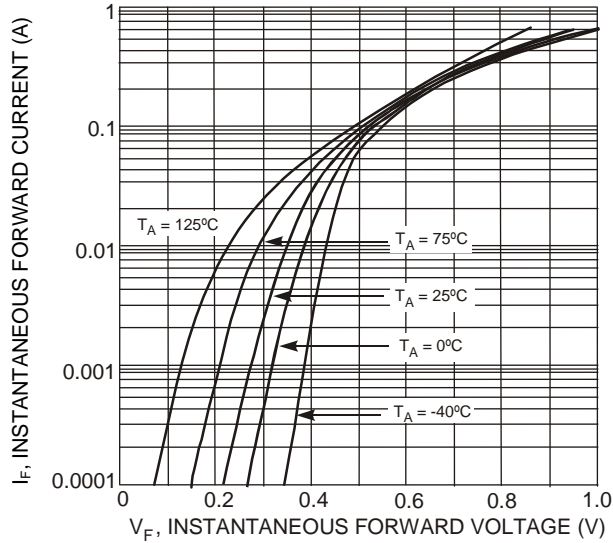
Thermal Characteristics

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 5)	P _D	200	mW
Typical Thermal Resistance Junction to Ambient Air (Note 5)	R _{θJA}	500	°C/W
Typical Thermal Resistance Junction to Case (Note 8)	R _{θJC}	180	°C/W
Operating and Storage Temperature Range (Note 6)	T _J , T _{STG}	-65 to +150	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 7)	V _{(BR)R}	30	—	—	V	I _{RS} = 100μA
Forward Voltage	V _F	—	—	240 320 400 500 800	mV	I _F = 0.1mA I _F = 1mA I _F = 10mA I _F = 30mA I _F = 100mA
Reverse Leakage Current (Note 7)	I _R	—	—	2.0	μA	V _R = 25V
Total Capacitance	C _T	—	—	10	pF	V _R = 1.0V, f = 1.0MHz
Reverse Recovery Time	t _{RR}	—	—	5.0	ns	I _F = 10mA through I _R = 10mA to I _R = 1.0mA, R _L = 100Ω

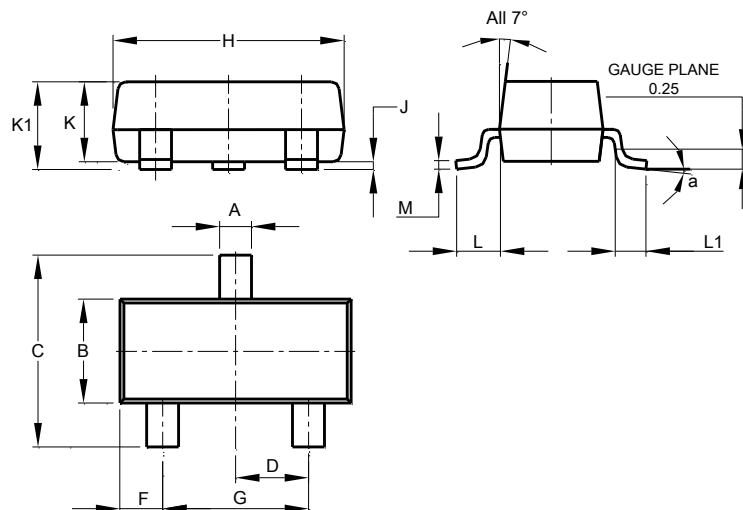
- Notes:
- Part mounted on FR-4 board with recommended pad layout, which can be found on our website at <http://www.diodes.com/package-outlines.html>.
 - The heat generated must be less than the thermal conductivity from Junction-to-Ambient: dP_D/dT_J < 1/R_{θJA}.
 - Short duration test pulse used to minimize self-heating effect.
 - Device mounted on Polyimide substrate PC board. FR-4 2oz 1*MRP layout.



Package Outline Dimensions

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

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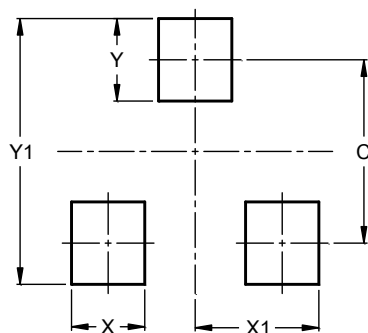


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Dim	Min	Max	Typ
A	0.37	0.51	0.40
B	1.20	1.40	1.30
C	2.30	2.50	2.40
D	0.89	1.03	0.915
F	0.45	0.60	0.535
G	1.78	2.05	1.83
H	2.80	3.00	2.90
J	0.013	0.10	0.05
K	0.890	1.00	0.975
K1	0.903	1.10	1.025
L	0.45	0.61	0.55
L1	0.25	0.55	0.40
M	0.085	0.150	0.110
a	0°	8°	--
All Dimensions in mm			

Suggested Pad Layout

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

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Dimensions	Value (in mm)
C	2.0
X	0.8
X1	1.35
Y	0.9
Y1	2.9

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